

HBR30L150YD

Low Vf Schottky Barrier Rectifiers



Voltage: 150 Volts

Current: 30 A

Package: TO-263

Features

- NH'S Low Vf Schottky Barrier Chip Technology
- Super Low Forward Voltage Drop For High Efficiency
- Low Power Loss For High Reliability
- High Frequency Switching Speed

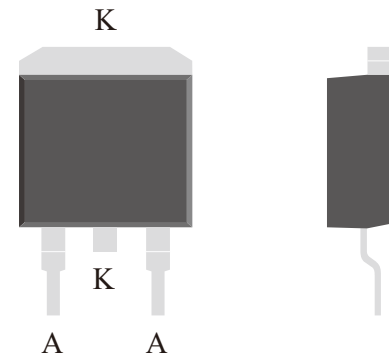
Mechanical Data

- **Case:** Molded With UL-94 ClassV-0 Recognized, RoHS-Compliant
- **Polarity:** Look At The Diagram And Polarity On The Right
- **Terminals:** Tin Plated Leads,Solderable Per J-STD-002 And JESD22-B102

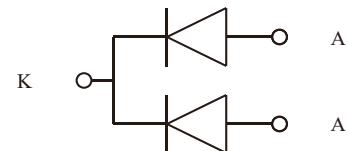
Typical Applications

- Switch Mode Power Supplies (SMPS)
- Fast Chargers
- LED Driver And Monitor Lighting
- Automotive Electronics And Charging Posts

Diagram:



Polarity:



Single Phase,Half Wave,60Hz,Resistive Or Inductive Load.For Capacitive Load,Derate Current By 20%

Maximum Ratings (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	150	V
Maximum RMS Voltag		V_{RMS}	105	V
Maximum DC Blocking Voltage		V_{DC}	150	V
Maximum Average Forward Rectified Current	Per Diode Total device	$I_{F(AV)}$	15 30	A
Peak Forward Surge Current Per Diode	8.3ms Single Half Sine-wave Superimposed On Rate Load	I_{FSM}	200	A
Current Squared Time Per Diode	$t < 8.3ms$	I^2t	166.0	A ² sec

Electrical Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings			Unit
			Min.	Typ.	Max.	
Instaneous Forward Voltage Per Diode	Ta=25°C Ta=100°C If= 15.0 A	V_F	-- --	0.85 0.81	0.9 0.86	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	Ta=25°C , $V_R=V_{RRM}$ Ta=90°C , $V_R=V_{RRM}*80\%$	I_{RRM}	-- --	1 1	5 2	uA mA
Typical Junction Capacitance Per Diode	4 V,1MHz	C_J	--	300	--	pF

Thermal Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Operating Junction Temperature Range		T_J	-55 to 175	°C
Storage Temperature Range		T_{STD}	-55 to 175	
Thermal Resistance Junction To Ambient With Steady-State	Still Air Environment With Ta=25°C	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance Junction-Case With Steady-State	Device Mounted On 1 in2 FR-4 Board With 2oz. Copper	$R_{\theta JC}$	2.0	

Notes: 1.Pulse Test: 300 Us Pulse Width,1% Duty Cycle

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Typical Characteristics Curves

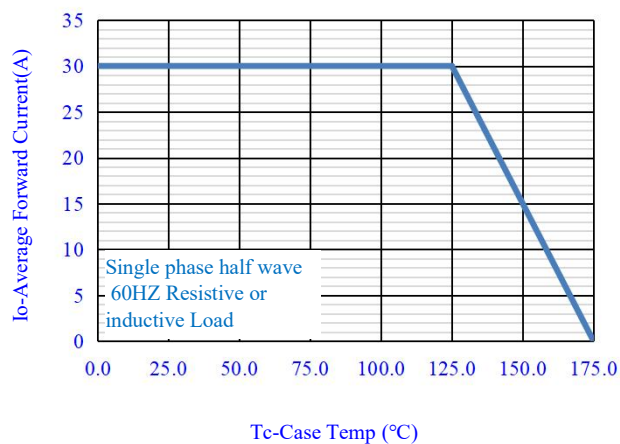


Fig.1-Forward Current Derating Curve

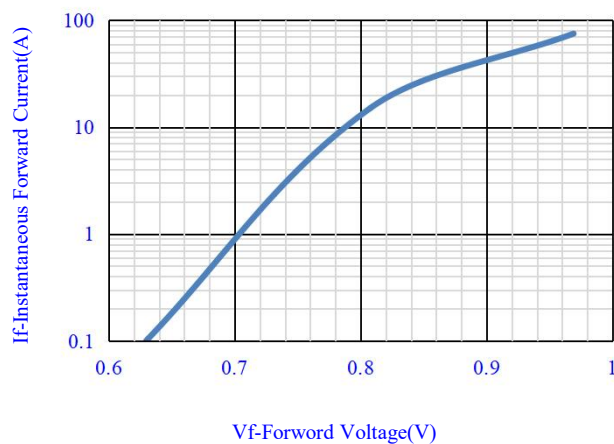


Fig.2-Typical Instantaneous Forward

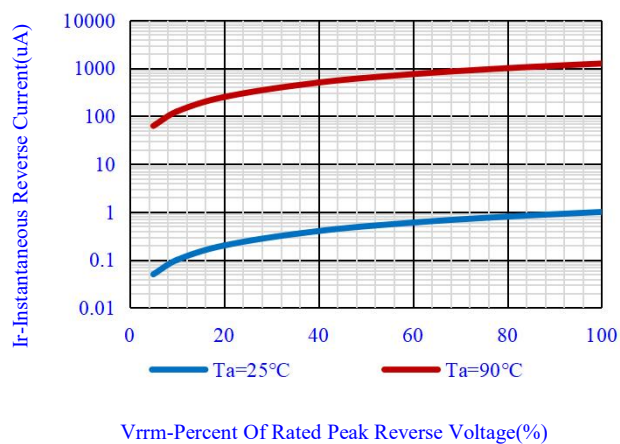


Fig.3-Typical Reverse Characteristics

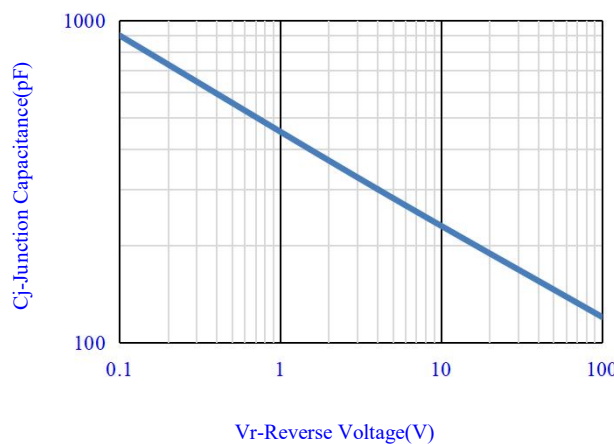


Fig.4-Typical Junction Capacitance

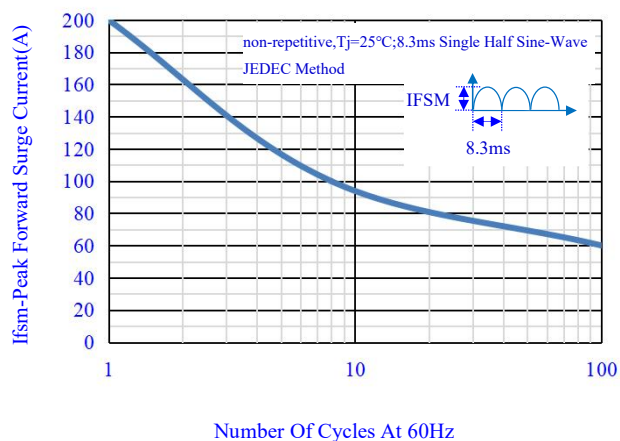


Fig.5-Max. Non-Repetitive Surge Current

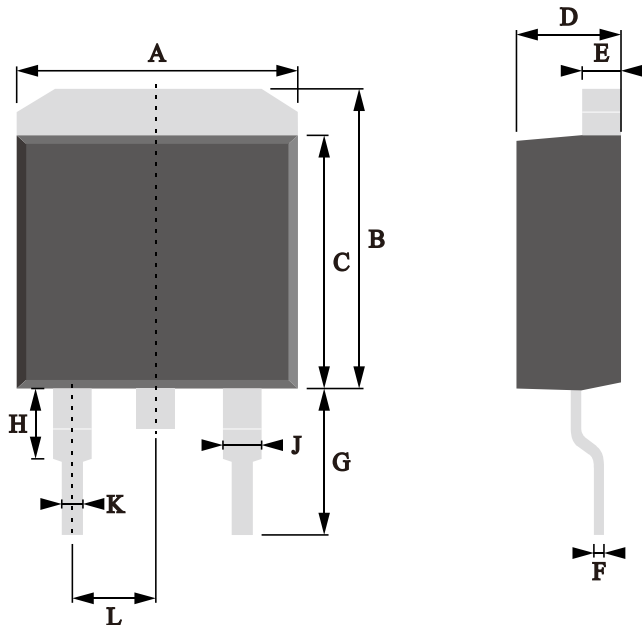
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OUTLINE DRAWINGS

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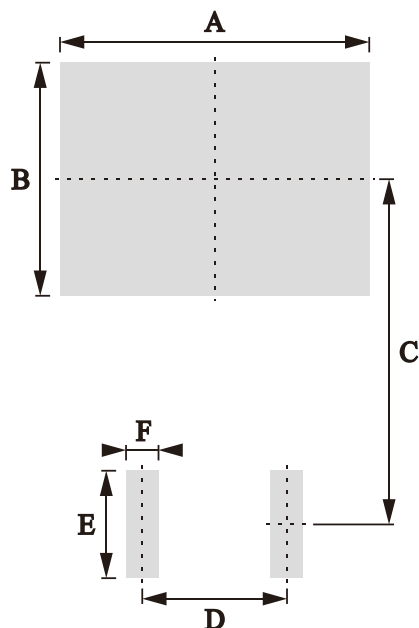


OUTLINE DIMENSIONS

Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.30	-	10.50	0.3661	-	0.4134
B	9.60	-	11.60	0.3780	-	0.4567
C	8.20	-	9.50	0.3228	-	0.3740
D	4.00	-	5.00	0.1575	-	0.1969
E	1.00	-	1.70	0.0394	-	0.0669
F	0.20	-	0.70	0.0079	-	0.0276
G	4.45	-	5.25	0.1752	-	0.2067
H	1.25	-	1.85	0.0492	-	0.0728
J	1.00	-	1.60	0.0394	-	0.0630
K	0.60	-	1.00	0.0236	-	0.0394
L	2.25	-	2.80	0.0886	-	0.1102

RECOMMEDND LAYOUT DRAWINGS

TO-263



OUTLINE DIMENSIONS

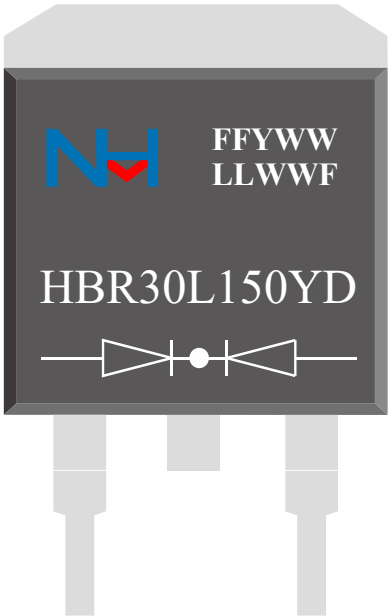
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	10.86	-	-	0.4276	-
B	-	7.86	-	-	0.3094	-
C	-	11.64	-	-	0.4583	-
D	-	5.08	-	-	0.2000	-
E	-	3.62	-	-	0.1090	-
F	-	1.14	-	-	0.0560	-

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MARKING



MARKING INSTRUCTION

NH=Niuhang Trademark
FF=Product Line Code,According To Actual Changes
YWW=Date Code,According To Actual Changes
LLWWF=Inernal Code,According To Actual Changes
HBR30L150YD=Model

PACKING INFORMATION

Package Type	Package Code	Product Weight Approx(g/Pcs)	Package Method	Quantity (Pcs/Min. Pack.)	Quantity (Pcs/Inner Box)	Quantity (Pcs/Carton)
TO-263	P1	1.4331	13" Reel	800	800	4800
TO-263	P2	1.4331	13" Reel	1000	1000	6000

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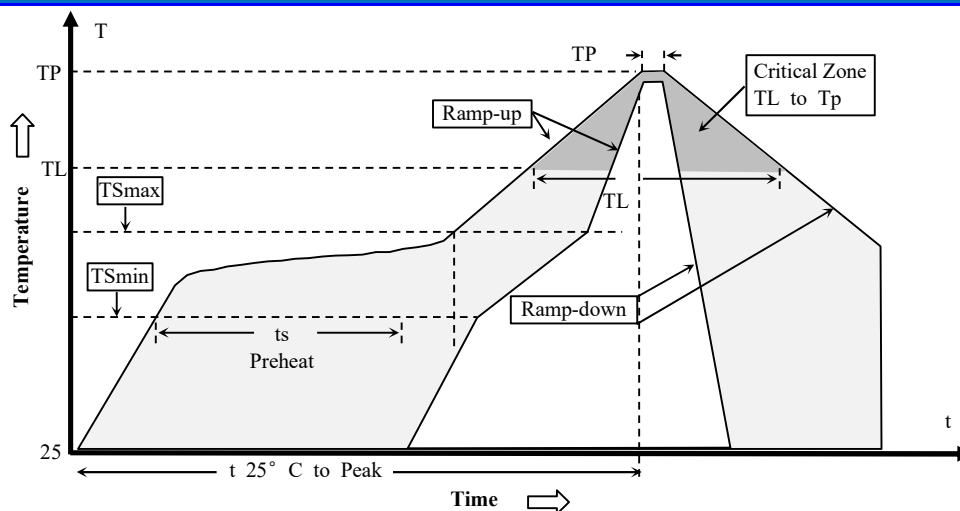
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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(TS min) -Temperature Max(TS max) -Time(ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (TL) - Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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